

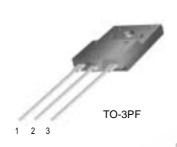
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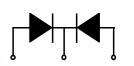
Features

- · Ultrafast with soft recovery
- Low forward voltage

Applications

- Power switching circuits





Power switchOutput rectifhFreewheelin	iers		
	ode power supply	1. Anode 2.Catho	ode 3. Anode
	FAST RECOVERY POWER RECTIFIE	B	
Absolute	Maximum Ratings (per diode) T _C =25°C unless otherwi	se noted	
Absolute Symbol			Units
Absolute	Maximum Ratings (per diode) T _C =25°C unless otherwi	se noted	Units V
Absolute Symbol	Maximum Ratings (per diode) T _C =25°C unless otherwi	se noted Value	
Absolute Symbol	Maximum Ratings (per diode) T _C =25°C unless otherwing Parameter Peak Repetitive Reverse Voltage	value 400	V

Thermal Characteristics

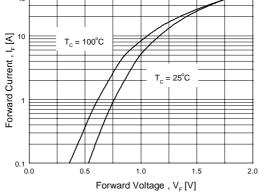
Symbol	Symbol Parameter		Units	
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	4.0	°C/W	

Electrical Characteristics (per diode) T_C=25 °C unless otherwise noted

Symbol	Parameter		Min.	Тур.	Max.	Units
V _{FM} *	Maximum Instantaneous Forward Voltage					V
	I _F = 10A	T _C = 25 °C	-	-	1.4	
	I _F = 10A	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	-	-	1.3	
I _{RM} *	Maximum Instantaneous Reverse Current					μΑ
	@ rated V _R	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	-	-	30	
		T _C = 100 °C	-	-	300	
t _{rr}	Maximum Reverse Recovery Time	•	-	-	50	ns
Irr	Maximum Reverse Recovery Current		-	-	4.5	Α
Q _{rr}	Maximum Reverse Recovery Charge (I _F =10A, di/dt = 200A/μs)		-	-	113	nC
W _{AVL}	Avalanche Energy		1.0	-	-	mJ

^{*} Pulse Test: Pulse Width=300μs, Duty Cycle=2%

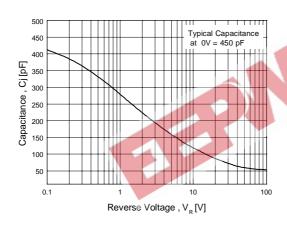
Typical Characteristics 40



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Figure 1. Typical Forward Voltage Drop vs. Forward Current

Figure 2. Typical Reverse Current vs. Reverse Voltage



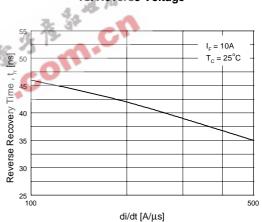
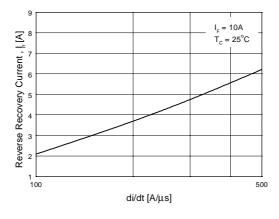


Figure 3. Typical Junction Capacitance

Figure 4. Typical Reverse Recovery Time vs. di/dt



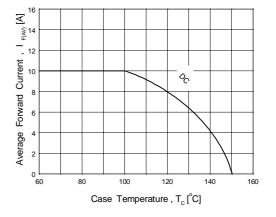


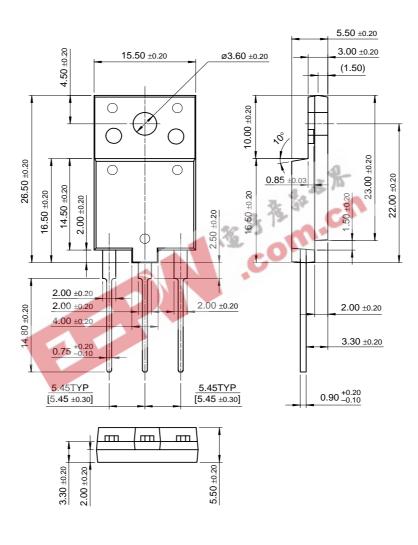
Figure 5. Typical Reverse Recovery Current vs. di/dt

Figure 6. Forward Current Derating Curve

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Package Dimensions

TO-3PF



Dimensions in Millimeters

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